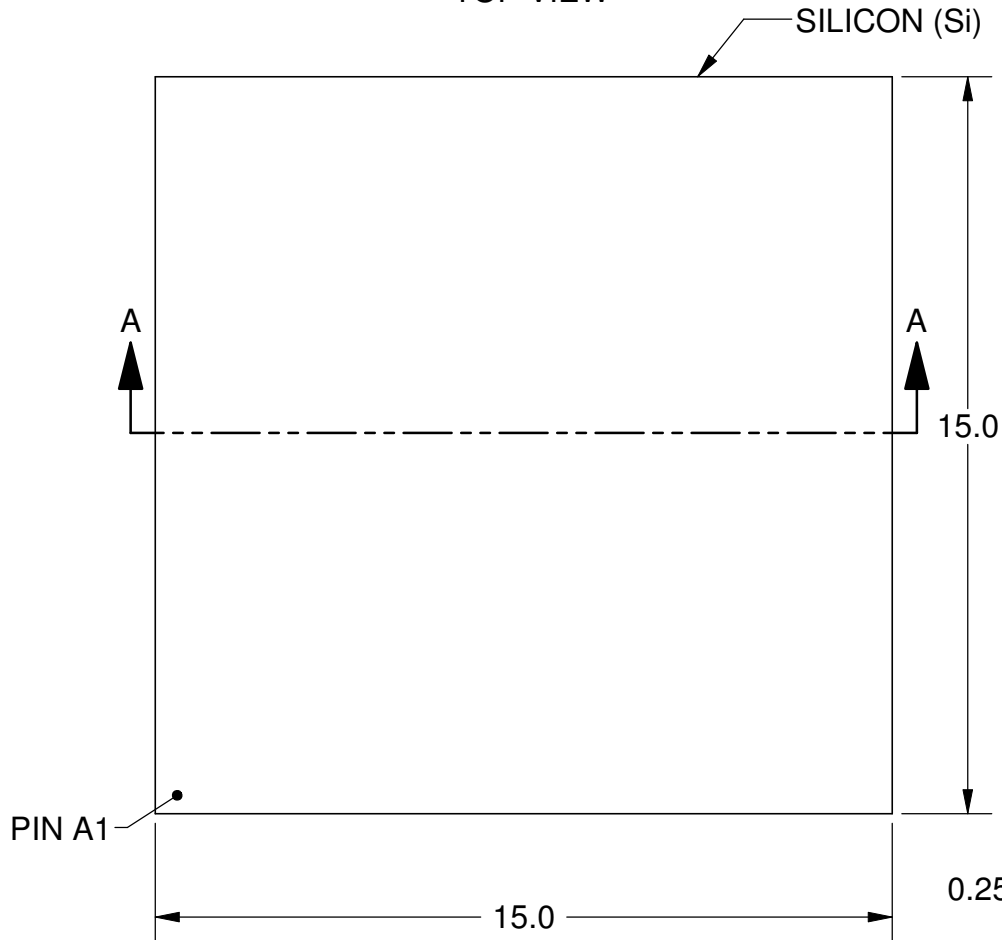
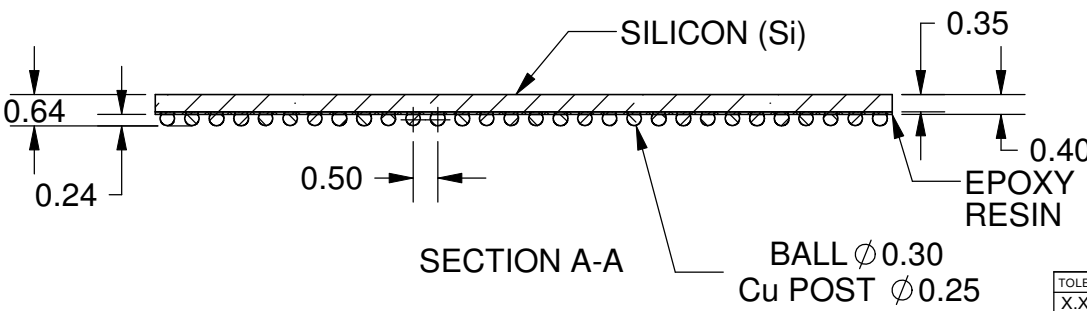
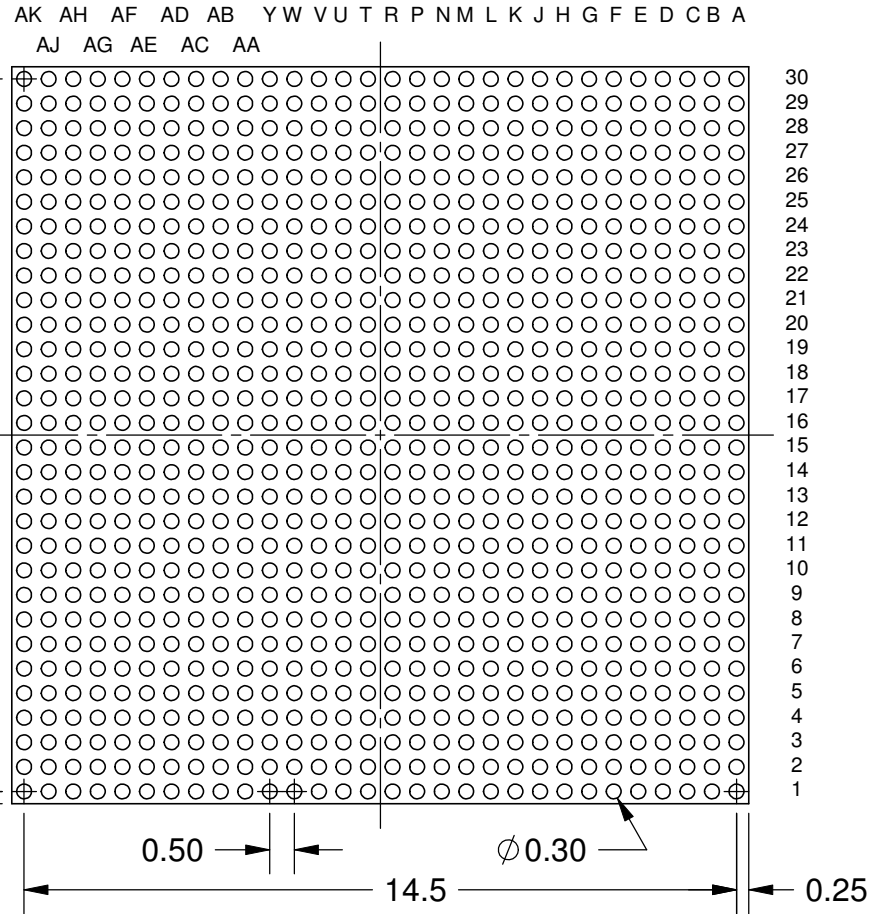


TOP VIEW



BALL VIEW



Notes: (Unless Otherwise Specified).

- 1) ALL DIMENSIONS ARE IN MM.
- 2) SOLDER BALL ALLOY:
STANDARD: SAC305 (Sn96.5/Ag3.0/Cu0.5).
SPECIAL: LF35 (Sn98.3/Ag1.2/Cu0.5).
- 3) BALL DIAMETER (BEFORE REFLOW): 0.30mm.
- 4) NON-SOLDER MASK DEFINED PAD.
- 5) PAD Cu DIAMETER: 0.25mm.
- 6) SUBSTRATE MATERIAL: Si (SILICON).
- 7) DAISY CHAIN PATTERN (SEE PAGE 2).

PART NUMBER TABLE

PART NUMBER	BALL ALLOY	Pb-FREE	RoHS	Si DIE
WLP900T.5C-DC307D	Sn96.5/Ag3.0/Cu0.5	YES	YES	YES
WLP900T.5C1-DC307D	Sn98.3/Ag1.2/Cu0.5	YES	YES	YES

TOLERANCE UNLESS NOTED		APPROVALS	DATE
X.X	+/- 0.3	DRAWN J. Hines	12/28/2010
X.XX	+/- 0.03		
X.XXX	+/- 0.003		
ANGLES +/- 0.5°		ENG	
ALL DIMENSIONS IN		MFG	
<input type="checkbox"/> INCHES <input checked="" type="checkbox"/> MILLIMETERS		QA	
THIRD ANGLE PROJECTION		CUST	
		REVISED	

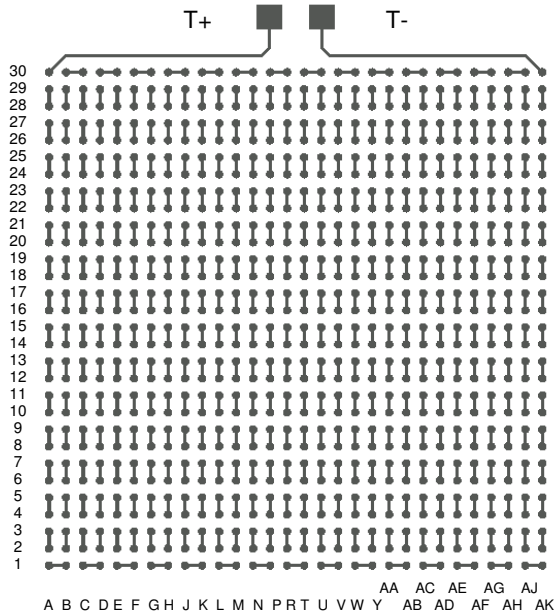
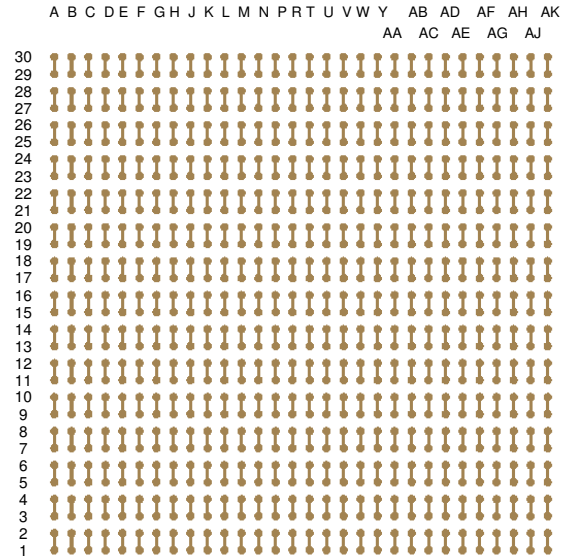
TITLE WLP900T.5C-DC307D			
900-BALL P=0.5mm (TEG0510)			
SCALE	SIZE	DRAWING NO.	REV
6.5:1	A	553072	A
DO NOT SCALE DRAWING			SHEET 1 OF 2

DAISY CHAIN PATTERN



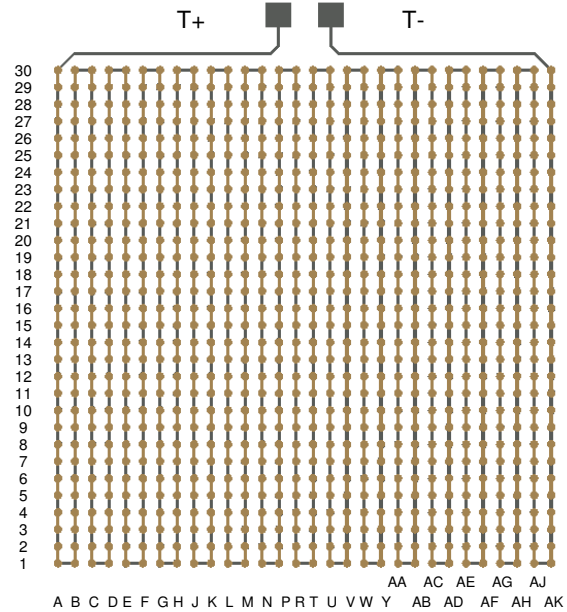
BALL VIEW

BOTTOM SIDE
(TOP X-RAY VIEW)



TOP VIEW

AFTER MOUNTING
TO TEST BOARD
(TOP X-RAY VIEW)



TEST VEHICLE BOARD

Notes:

- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
- 2) PCB Cu BALL PAD DIAMETER 0.25mm (9.8mil).
- 3) PCB DAISY CHAIN TRACING LINE WIDTH 0.10mm (3.9mil).

TopLine ®			
TITLE WLP900T.5C-DC307D 900-BALL P=0.5mm (TEG0510)			
SCALE 4.5:1	SIZE A	DRAWING NO. 553072	REV A
DO NOT SCALE DRAWING		SHEET 2 OF 2	